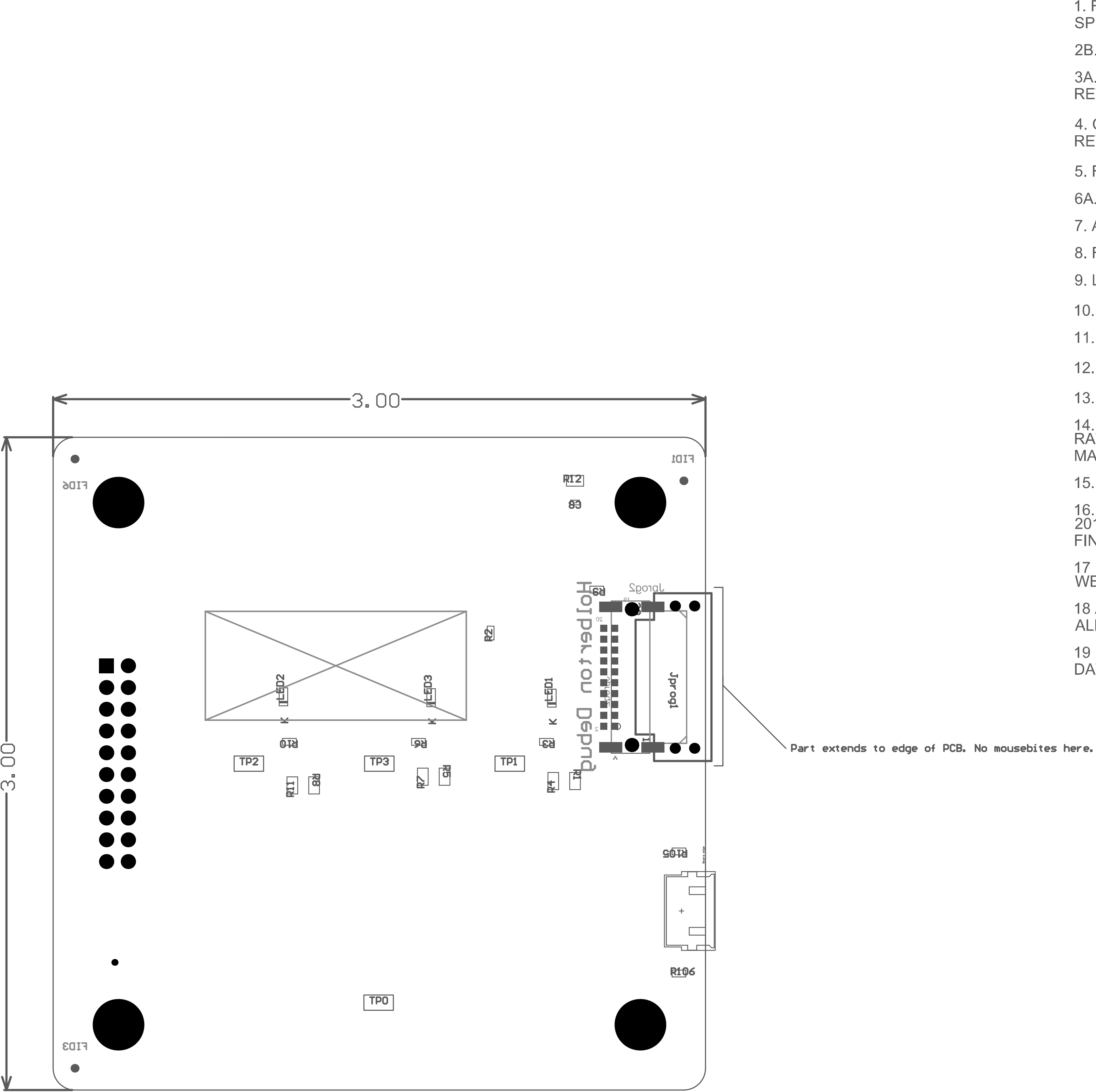


1. FABRICATE TO MEET IPC-2221, IPC-6011, AND IPC-6012 (LATEST REVISIONS) CLASS 2, EXCEPT WHERE OTHERWISE SPECIFIED.
- 2B. IMPEDANCE OF TRACES CONTROLLED BY WIDTHS: 9.4MIL, 50 OHM MICROSTRIP SINGLE ENDED.
- 3A. MATERIAL: COPPER CLAD LAMINATE AND PREPREG PER IPC-4101/126, IPC-4101/130, OR IPC-4101/131 (LATEST REVISION). 370HR MEETS THIS REQUIREMENT. PCB LAMINATE SHALL BE ROHS AND REACH COMPLIANT.
4. COPPER WEIGHT: COPPER LAYERS SHALL MATCH STACKUP TABLE WITH COPPER THICKNESS PER IPC-4562 (LATEST REVISION).
5. FINAL BOARD THICKNESS SHALL BE $\pm 10\%$ OF STACKUP TABLE, INCLUDING OUTER COPPER LAYERS.
- 6A. THIEVING PATTERN SHALL NOT BE ADDED TO THE PCB UNLESS SPECIFICALLY APPROVED IN WRITING.
7. ALL DIMENSIONS, INCLUDING HOLE SIZE DIMENSIONS, APPLY AFTER PLATING.
8. FINAL CONDUCTOR WIDTH SHALL BE $\pm 20\%$ OF DATA.
9. LAYER TO LAYER REGISTRATION SHALL BE WITHIN 0.15MM (0.005 IN) OF DATA.
10. ALL HOLES SHALL BE LOCATED WITHIN ± 0.003 INCHES OF SPECIFIED COORDINATES.
11. PLATING SHALL BE ENIG PER IPC-4552 (LATEST REVISION).
12. SOLDER MASK BOTH SIDES PER IPC-SM-840 (LATEST REVISION), CLASS T OR FT, COLOR GREEN.
13. BOARDS SHALL BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.
14. SUPPLIER SHALL MARK STACKUP AND DATE CODE, SUPPLIER NAME AND/OR TRADEMARK, AND UL FLAMMABILITY RATING IN NON-CONDUCTIVE INDELIBLE INK (COLOR WHITE OR BLACK). SUPPLIER SHALL NOT ADD ANY TEXT OR MARKING IN COPPER.
15. SILKSCREEN OVER SOLDER MASK SHALL BE COLOR WHITE.
16. THE MATERIALS AND PROCESS USED TO FABRICATE THIS PART ARE TO BE CONSISTENT WITH THE DIRECTIVE 2011/65/EU RESTRICTION OF HAZARDOUS SUBSTANCES IN ELECTRICAL AND ELECTRONIC EQUIPMENT (ROHS). THE FINISHED PART TO BE ACCOMPANIED BY A SIGNED CERTIFICATE OF COMPLIANCE TO DIRECTIVE 2011/65/EU.
- 17 IF ANY REACH SVHC'S ARE UTILIZED IN THE MATERIALS AND/OR PROCESS USED TO FABRICATE THIS PART, THE WEIGHT OF THE SVHC'S MUST BE PROVIDED.
- 18 A CONFLICT MINERALS REPORTING TEMPLATE (CMRT) MUST BE AVAILABLE UPON REQUEST AT A PART LEVEL FOR ALL SUPPLIED PARTS.
- 19 HOMOGENEOUS SUBSTANCE INFORMATION TO ACCOMPANY THE FABRICATED PART PER IPC-1752 (LATEST REV) DATA STANDARDS.

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.80mil	3.5	
1	1Top Layer		1.35mil		
	Prepreg1	370HR	4.71mil	4.04	
2	2Mixed		1.35mil		
	Core1	370HR	22.60mil	4.04	
3	3Mixed		1.35mil		
	Prepreg2	370HR	4.71mil	4.04	
4	4Bottom Layer		1.35mil		
	Bottom Solder	Solder Resist	0.80mil	3.5	
	Bottom Overlay				



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	Bottom Overlay				